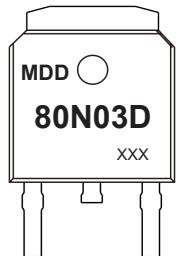


V_{(BR)DSS}	R_{DS(on)Max}	I_{D Max}
30V	6mΩ@10V	80A
	9mΩ@4.5V	

Features

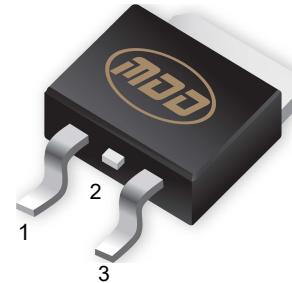
- Trench Power LV MOSFET technology
- Excellent package for heat dissipation
- High density cell design for low R_{DS(ON)}
- Halogen Free

Marking



XXX: Date Code

TO-252

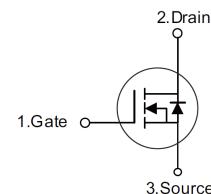


1. Gate
2. Drain
3. Source

Application

- High current load applications
- Load switching
- Hard switched and high frequency circuits
- Uninterruptible power supply

Equivalent Circuit



Absolute Maximum Ratings (T_A=25°C unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V _{DS}	30	V
Gate-Source Voltage	V _{GS}	±20	V
Continuous Drain Current	I _D	80	A
Pulsed Drain Current (Note 1)	I _{DM}	190	A
Avalanche Energy Single Pulsed (Note 2)	E _{AS}	132	mJ
Power Dissipation	P _D	44	W
Thermal Resistance Junction-to-Case(Note 3)	R _{θJC}	2.8	°C/W
Junction Temperature	T _J	150	°C
Storage Temperature	T _{stg}	-50 ~+150	°C

Notes: 1.Pulse Test: Pulse Width≤300us,Duty cycle ≤2%.

2.T_j=25°C, V_{DD}=25V, V_G=10V, L=0.5mH, I_{AS}=23A

3.R_{θJA} is the sum of the junction-to-case and case-to-ambient thermal resistance, where the case thermal reference is defined as the solder mounting surface of the drain pins. R_{θJC} is guaranteed by design, while R_{θJA} is determined by the board design. The maximum rating presented here is based on mounting on a 1 in 2 pad of 2oz copper.



MDD80N03D

30V N-Channel Enhancement Mode MOSFET

T_a = 25°C unless otherwise specified

Symbol	Parameter	Condition	Min	Typ	Max	Unit
V _{(BR)DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250μA	30	--	--	V
I _{DS}	Drain-Source Leakage Current	V _{DS} =30V, V _{GS} =0V	--	--	1	uA
I _{GSS}	Gate-Source Leakage Current	V _{GS} =±20V, V _{DS} =0V	--	--	±100	nA
V _{GS(TH)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250μA	1.0	1.5	2.5	V
R _{DS(ON)}	Drain-Source On-State Resistance	V _{GS} =10V, I _D =20A	--	3.8	6	mΩ
		V _{GS} =4.5V, I _D =15A	--	4.8	9	mΩ

Dynamic Electrical Characteristics

Symbol	Parameter	Condition	Min	Typ	Max	Unit
C _{iss}	Input Capacitance	V _{DS} =15V V _{GS} =0V f=1MHz	--	2504	--	pF
C _{oss}	Output Capacitance		--	323	--	pF
C _{rss}	Reverse Transfer Capacitance		--	283	--	pF
Q _g	Total Gate Charge	V _{DS} =15V, V _{GS} =10V, I _D =20A (Note1,2)	--	54	--	nC
Q _{gs}	Gate Source Charge		--	8.5	--	nC
Q _{gd}	Gate Drain Charge		--	10.2	--	nC

Switching Characteristics

Symbol	Parameter	Condition	Min	Typ	Max	Unit
t _{d(on)}	Turn on Delay Time	V _{DS} =20V, V _{GS} =10V, I _D =2A, R _G =3Ω (Note1,2)	--	11.4	--	ns
t _r	Turn on Rise Time		--	20.4	--	ns
t _{d(off)}	Turn Off Delay Time		--	41	--	ns
t _f	Turn Off Fall Time		--	25	--	ns

Source Drain Diode Characteristics

Symbol	Parameter	Condition	Min	Typ	Max	Unit
I _{SD}	Source drain current(Body Diode)		--	--	80	A
I _{SM}	Pulsed Current		--	--	190	A
V _{SD}	Drain-Source Diode Forward Voltage	I _S =20A, V _{GS} =0V	--	0.8	1.2	V
t _{rr}	Body Diode Reverse Recovery Time	I _F =20A, V _{GS} =0V, dI/dt=100A/μs	--	15.1	--	ns
Q _{rr}	Body Diode Reverse Recovery Charge		--	6.5	--	nC

Notes: 1.Pulse test ; Pulse width 300us, duty cycle 2%.

2.Essentially independent of operating temperature.

■ Typical Performance Characteristics

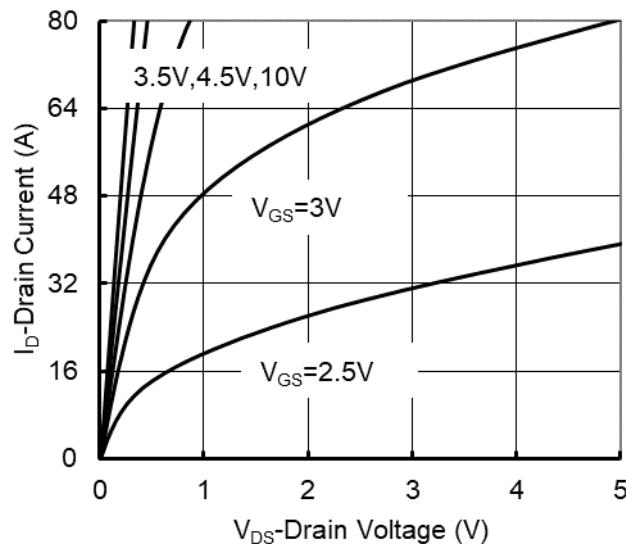


Figure 1. Output Characteristics

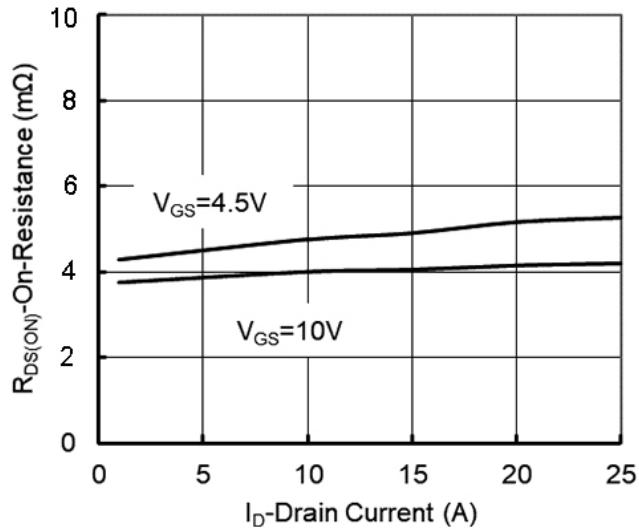


Figure 3. On-Resistance vs. Drain Current and Gate Voltage

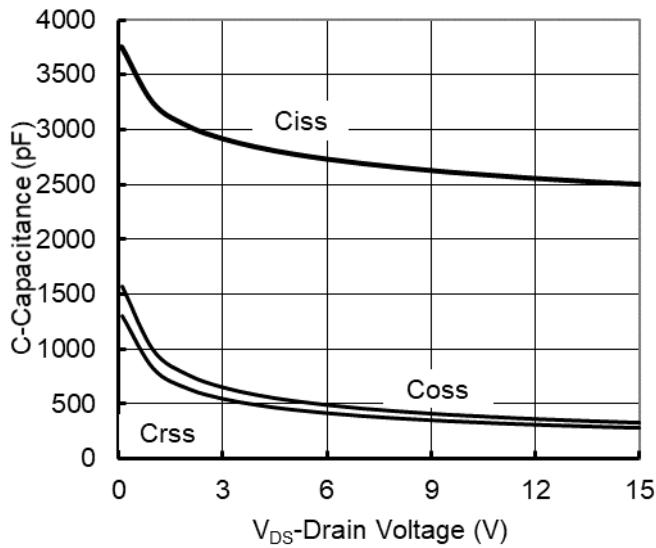


Figure 5. Capacitance Characteristics

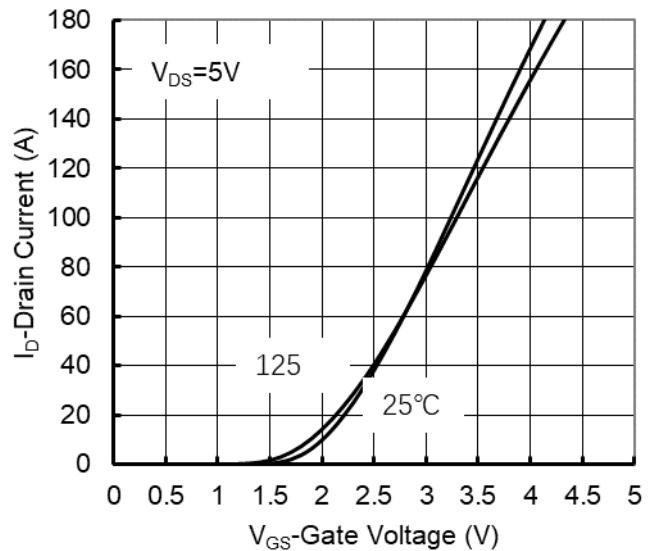


Figure 2. Transfer Characteristics

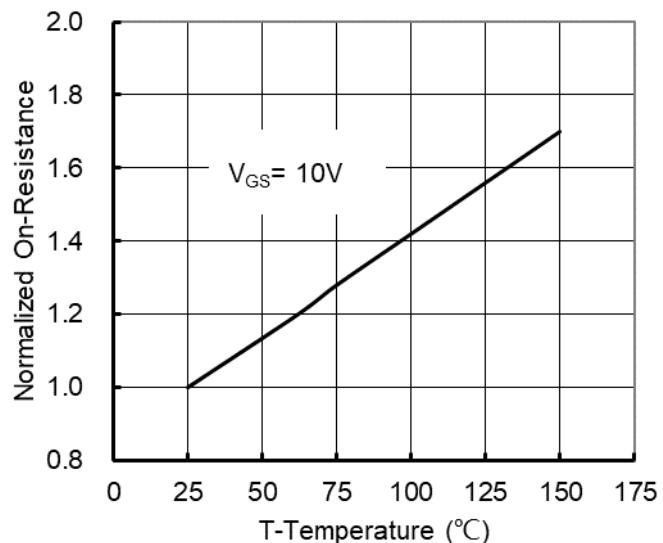


Figure 4. On-Resistance vs. Junction Temperature

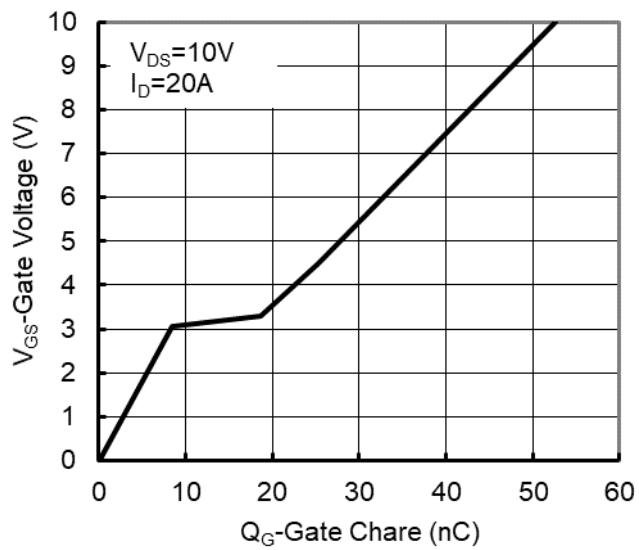
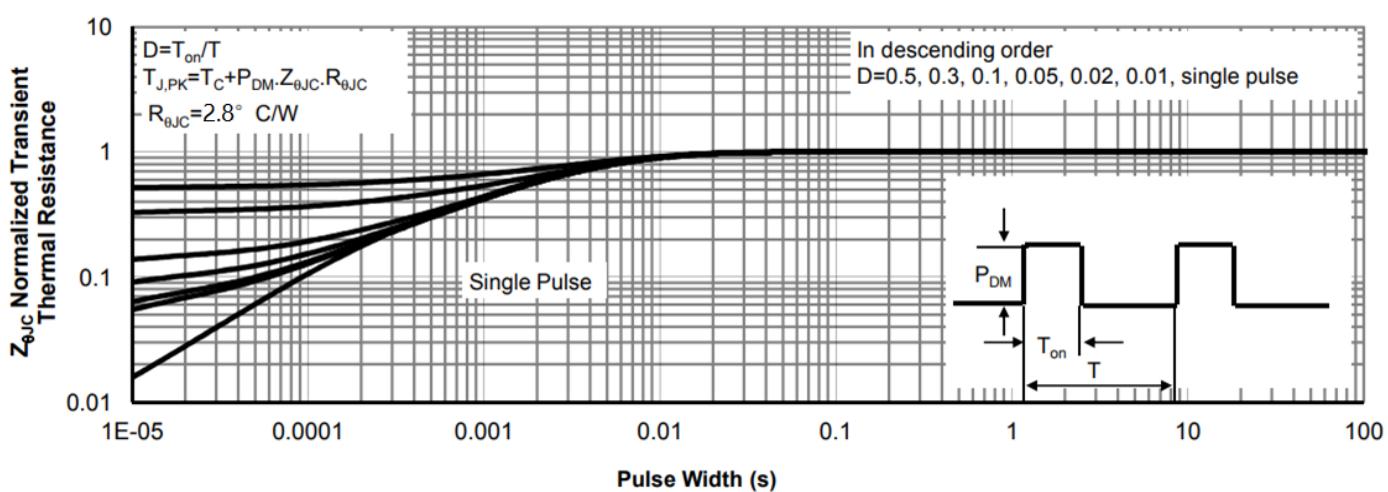
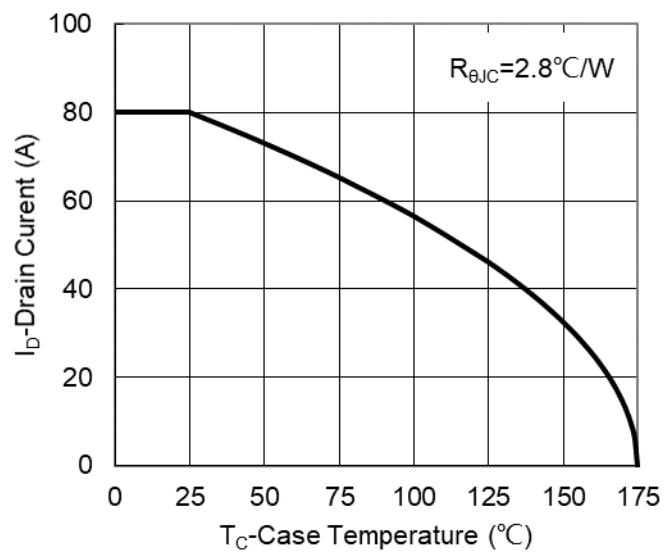
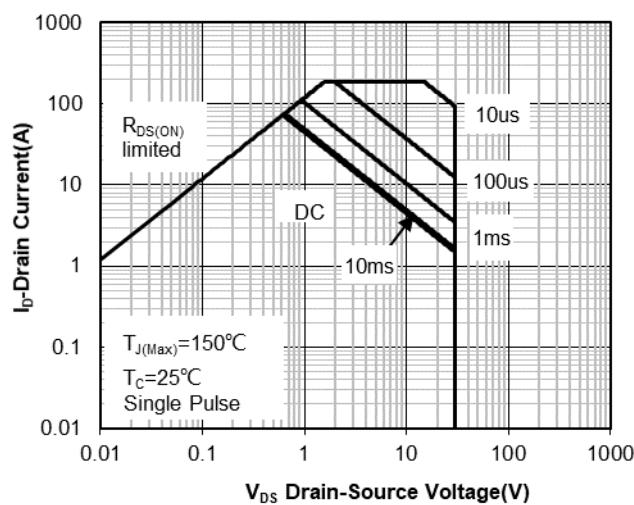
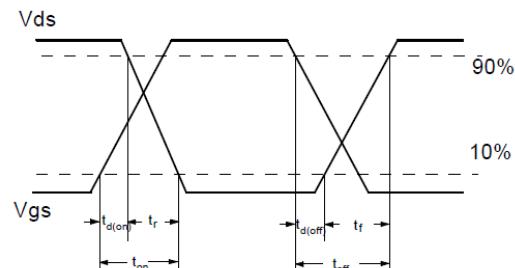
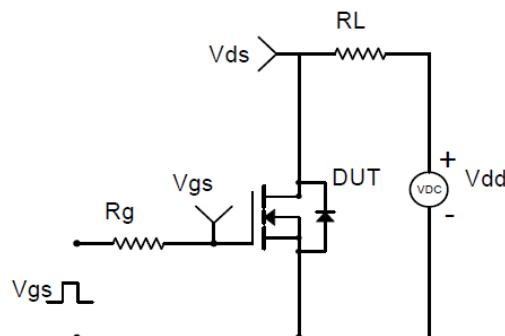
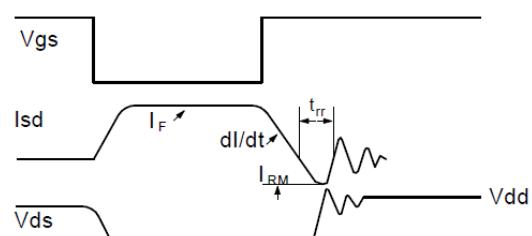
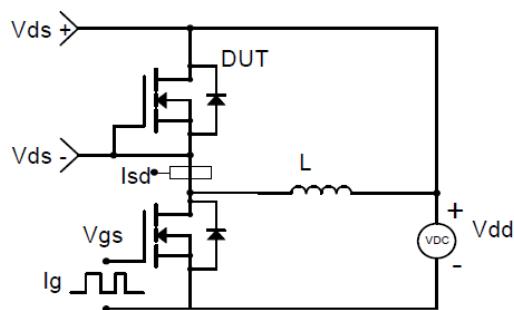
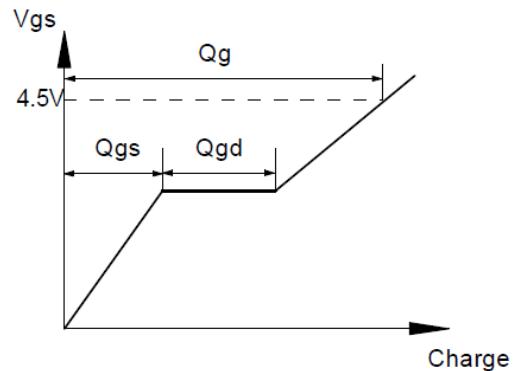
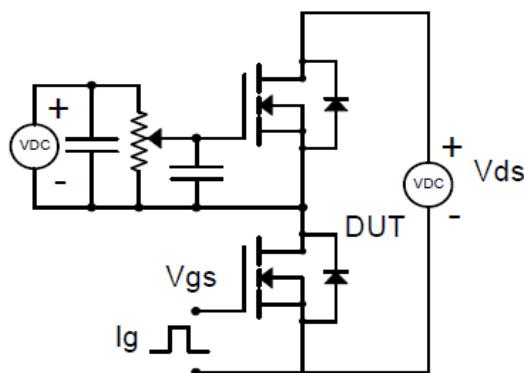
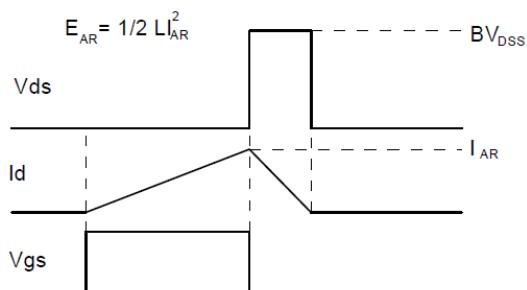
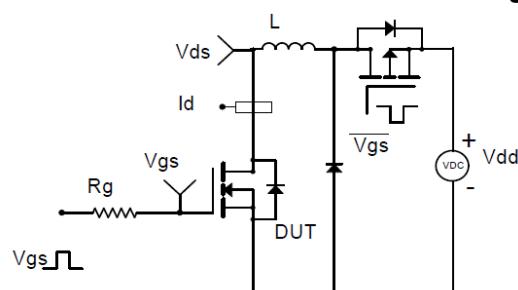


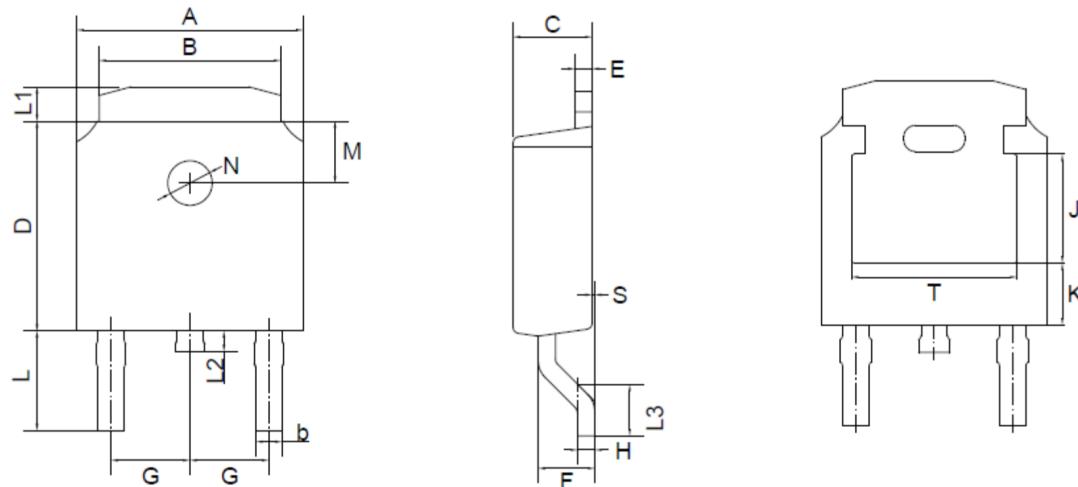
Figure 6. Gate Charge




Resistive Switching Test Circuit & Waveforms

Diode Recovery Test Circuit & Waveforms

Gate Charge Test Circuit & Waveform

Unclamped Inductive Switching (UIS) Test Circuit & Waveforms

Outline Drawing

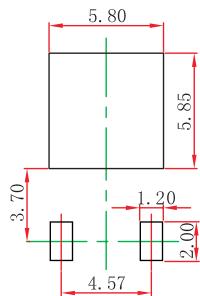
TO-252 Package Outline Dimensions



TO-252(D-PAK) mechanical data

UNIT	A	B	b	C	D	E	F	G	H	L	L1	L2	L3	S	M	N	J	K	T	
mm	max	6.7	5.5	0.8	2.5	6.3	0.6	1.8	2.29	0.55	3.1	1.2	1.0	1.75	0.1	1.8	1.3	3.16	1.80	4.83
	min	6.3	5.1	0.3	2.1	5.9	0.4	1.3		0.45	2.7	0.8	0.6	1.40	0.0					
mil	max	264	217	31	98	248	24	71	90	22	122	47	39	69	4	71	51	124	71	190
	min	248	201	12	83	232	16	51		18	106	31	24	55	0					

Suggested Pad Layout



Note:

1. Controlling dimension: in millimeters.
2. General tolerance: ± 0.05 mm.
3. The pad layout is for reference purposes only.

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[MCQ7328-TP](#) [SSM3J143TU,LXHF](#) [DMN12M3UCA6-7](#) [PJMF280N65E1_T0_00201](#) [PJMF380N65E1_T0_00201](#)
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